

Application Serial No: 10/552,301  
Responsive to the Office Action mailed on: April 10, 2007

### REMARKS

This is in response to the Office Action mailed on April 10, 2007. Claims 1-9 are pending.

#### §102 Rejections:

Claims 1-9 are rejected as being anticipated by Toshihiro (JP Publication No. 08-64401). This rejection is traversed.

Claim 1 is directed to a chip resistor that requires, among other features, a resistor element including an electrode-forming surface, at least two electrodes provided at the electrode forming surface and an insulating layer provided at the electrode-forming surface.

Toshihiro does not disclose or teach or suggest these features. Toshihiro is directed to a chip-like electronic part that includes a resistor layer (4), a ceramic substrate (1), electrode layers (2, 3 and 6) and an insulation layer (8) separated from the resistor layer (4) (see Abstract). The rejection interprets the ceramic substrate (1) as the electrode-forming surface, the resistor layer (4) as the resistor element, the electrode layers (2, 3 and 6) as the at least two electrodes and the insulation layer (8) as the insulating layer of claim 1, respectively. However, the ceramic substrate (1) is a substrate that is separate from and not a part of the resistor layer (4). Thus, the ceramic substrate (1) of Toshihiro cannot be the electrode-forming surface of claim 1. Under a proper interpretation of Toshihiro, only the bottom surface of the resistor layer (4) could be the electrode-forming surface of claim 1. Yet, under this interpretation the bottom surface of the resistor layer (4) completely abuts the ceramic substrate (1). Accordingly, Toshihiro also cannot disclose or suggest at least two electrodes provided at an electrode-forming surface or an insulating layer provided at an electrode-forming surface, as required by claim 1. For at least these reasons claim 1 is not suggested by Toshihiro. Claims 2-4 depend from claim 1 and should be allowed for at least the same reasons.

Claim 5 is directed to a method for manufacturing a chip resistor that requires, inter alia, pattern-forming an insulating layer on an electrode-forming surface of a resistor element material and forming a conductive layer on the electrode-forming surface at a region where the insulating layer is not formed, the conductive layer having a

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thickness which is equal or generally equal to a thickness of the insulating layer. Claim 5 also requires dividing the resistor element material into a plurality of resistor elements each in the form of a chip. Furthermore, the division of the resistor element material is so performed that each of the resistor elements in the form of a chip includes part of the insulating layer and electrode portions spaced from each other by the part of the insulating layer.

Toshihiro does not disclose or teach or suggest these features. Toshihiro is directed to a chip-like electronic part that includes a resistor layer (4), a ceramic substrate (1), electrode layers (2, 3 and 6) and an insulation layer (8) separated from the resistor layer (4) (see Abstract). Nowhere does the rejection indicate where Toshihiro discloses or suggests a method for manufacturing a chip resistor, as required by claim 5. Moreover, even if Toshihiro discloses a method for manufacturing a chip resistor, nowhere does Toshihiro disclose or suggest pattern-forming an insulating layer on an electrode-forming surface of a resistor element material or that the division of the resistor element material is so performed that each of the resistor elements in the form of a chip includes part of the insulating layer and electrode portions spaced from each other by the part of the insulating layer, as required by claim 5, as the bottom surface of resistor layer (4) completely abuts the ceramic substrate (1). For at least these reasons claim 5 is not suggested by Toshihiro. Claims 6-9 depend from claim 5 and should be allowed for at least the same reasons.

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Conclusion:

Applicant respectfully asserts that claims 1-9 are now in condition for allowance. In view of the above, early issuance of a notice of allowance is solicited. Any questions regarding this communication can be directed to the undersigned attorney, Curtis B. Hamre, Reg. No. 29,165 at (612) 455-3802.



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